



ISOCC 2024

21th International SoC Design Conference

August 19-22, 2024

**Premier Hotel Tsubaki,
Sapporo Japan**



**SAPPORO
BUSINESS
EVENTS**



WELCOME MESSAGE

It is a great pleasure to invite you to the 21st International SoC Conference (ISOCC2024), which will be held from August 19th to 22nd, 2024 at Tsubaki Hotel in Sapporo, Hokkaido, Japan. This conference stands among the most highly acclaimed annual events in the System-on-Chip (SoC) Design field. We are truly glad to host this event in Sapporo, Japan. Since its inception, ISOCC has showcased the latest innovations and trends in the semiconductor SoC domain, drawing active participation from global researchers in academia, industry, and research institutes. The organizing and technical committee of ISOCC2024 is preparing for an exciting and advanced program including plenary speeches, invited talks, tutorials, technical paper presentations, and various research programs.

Sapporo, the largest city on Japan's northern island of Hokkaido, is renowned for its refreshing summer climate, parks, and gardens. Sapporo's eminent attractions include Odori Park, which stretches across the heart of the city, the historic Sapporo Clock Tower, Moerenuma Park designed by Isamu Noguchi, and the renowned Sapporo Beer Museum. Whether you are visiting for the first time or are familiar with its charms, Sapporo promises an unforgettable experience.

All members of the ISOCC 2024 organizing committee eagerly anticipate your presence and the valuable research contributions you'll bring to ISOCC 2024 in Sapporo. We cordially invite you to join us at ISOCC2024, where you will be sure to have a meaningful experience with industry professionals and scholars from around the world.

Seokhyeong Kang

General Chair, ISOCC 2024
Professor, Pohang University of Science and Technology



INTRODUCTION

ISOCC has established a long tradition as an annual conference providing the premier SoC design forum for worldwide researchers from academia and industries. Since its inception, ISOCC has been continuing to showcase the most recent innovations and trends in the semiconductor system-on-a-chip area with active participations from worldwide researchers in academia, industry, and institutes. ISOCC 2024 welcomes technical papers in the field of semiconductor circuits and systems presenting new advanced concept and developments in analog and digital circuit and system design, theory, simulation, modeling, experimental implementations and experiences, and emerging technologies in the system-on-a-chip area.

HISTORY

No.	Conference	Venue
1 st	ISOCC 2004	COEX Conference Center, Seoul, Korea
2 nd	ISOCC 2005	COEX Conference Center, Seoul, Korea
3 rd	ISOCC 2006	COEX Conference Center, Seoul, Korea
4 th	ISOCC 2007	COEX Conference Center, Seoul, Korea
5 th	ISOCC 2008	BEXCO Convention Hall, Busan, Korea
6 th	ISOCC 2009	BEXCO Convention Hall, Busan, Korea
7 th	ISOCC 2010	Songdo Convensia, Incheon, Korea
8 th	ISOCC 2011	Ramada Plaza Jeju Hotel, Jeju, Korea
9 th	ISOCC 2012	Ramada Plaza Jeju Hotel, Jeju, Korea
10 th	ISOCC 2013	BEXCO Convention Hall, Busan, Korea
11 th	ISOCC 2014	Ramada Plaza Jeju Hotel, Jeju, Korea
12 th	ISOCC 2015	Hotel Hyundai, Gyeongju, Korea
13 th	ISOCC 2016	Ramada Plaza Jeju Hotel, Jeju, Korea
14 th	ISOCC 2017	Grand Hilton Seoul, Seoul, Korea
15 th	ISOCC 2018	Inter-Burgo Hotel Daegu, Daegu, Korea
16 th	ISOCC 2019	Ramada Plaza Jeju Hotel, Jeju, Korea
17 th	ISOCC 2020	Sono Calm Yeosu Hotel, Yeosu, Korea
18 th	ISOCC 2021	Ramada Plaza Jeju Hotel, Jeju, Korea
19 th	ISOCC 2022	Lakai Sandpine Resort, Gangwon-do, Korea
20 th	ISOCC 2023	Ramada Plaza Jeju Hotel, Jeju, Korea



PRELIMINARY PROGRAM SCHEDULE

	August 19 (Mon.)	August 20 (Tue.)	August 21 (Wed.)	August 22 (Thur.)
Morning	-	Registration Opening Ceremony Keynote Speech	Registration Keynote Speech	Discussion
Afternoon	Registration Tutorials	Chip Design Contest Parallel Sessions Short Tutorial Industrial Exhibition	WiCAS Parallel Sessions Short Tutorial Industrial Exhibition	-
Evening	Welcome Reception	Banquet	Closing Ceremony	-

*This is NOT the final program. The program is subject to change.

TOPICS OF INTEREST

*Topics include, but are not limited to:

- Analog Circuits
- Data Converters
- RF/Microwave/Wireless
- Wireline
- Digital Circuits, Architecture, and Systems
- Machine Learning and AI
- SoC Design Methodology and CAD
- Circuits and Systems for Emerging Technologies



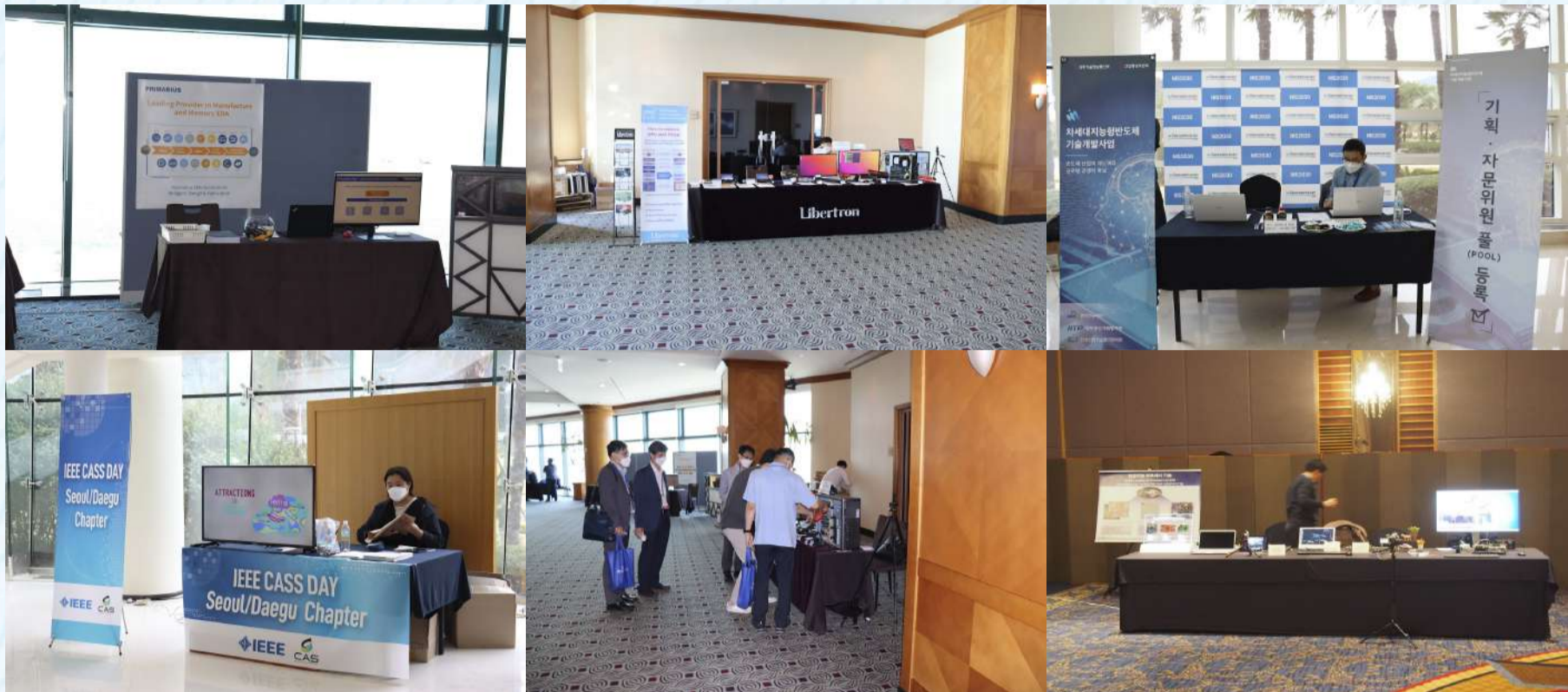
SPONSORSHIP PACKAGES

Level and Benefits	Diamond	Platinum	Gold	Silver	Bronze	Honor
	KRW 15,000,000	KRW 10,000,000	KRW 5,000,000	KRW 3,000,000	KRW 2,000,000	KRW 1,000,000
Advertising on Program Book (A5 Size, Color)	○ Back Cover (First Come, first served)	○ Inside the Back Cover (First Come, first served)	○	○	○	○
Advertising on Proceeding (A4 Size, PDF, Color)	○	○	○	○	○	○
Logo(CI) on Homepage	○	○	○	○	○	○
Exhibition Table Provided (a table, a chair, a backboard)	○	○	○	○	○	○
Free Registration	15 persons	10 persons	5 persons	3 persons	2 persons	1 person
Write the name of the sponsor in each session in the program book	5 sessions	4 sessions	3 sessions	2 sessions	1 session	×
Best Paper Award in the Name of the Sponsor	○	○	○	○	×	×
Logo on Proceeding USB	○	○	○	×	×	×
Logo on Name Badge	○	○	×	×	×	×

PLEASE NOTE

- *All advertisements and logos except for the back cover (out, in) are written in alphabetical order within the same grade.
- *Advertisement and logo (CI) files must be sent as illustration (AI) files or files with a resolution of 300dpi or higher.
- *The ad sizes are as follows:
 - Program Book: 148mm wide x 210mm high (A5 size)
 - Proceeding: 210mm wide x 297 mm high (A4 size)
- *The Sponsorship Packages are subject to change.

SPONSORED EXHIBITION



APPLICATION GUIDELINE

1) Application Information

- Submit the completed application form along with the business license to the ISOCC 2024 secretariat office via e-mail (secretary@isocc.org).
- The applicant is responsible for any bank service charge or money transfer fees.
- Total amount of sponsorship fee is subject to change by the organizing committee.
- As for the allocation of sponsors and exhibition table locations, priority will be based first on the sponsorship grade, then the deposit payment date, and lastly the application date.

2) Contact Information

ISOCC 2024 SECRETARIAT

#1736, Dukmyung B/D, 625, Teheran-ro, Gangnam-gu, Seoul, 06173, South Korea

Tel: +82-2-757-0981

Email: secretary@isocc.org



APPLICATION FORM

1) Registering Company and Person in Charge

Company Name			
Contact Person Name			
Department		Job Title	
Address			
Telephone			
E-mail		Homepage	

2) Application

Category	Amount (KRW)	Check for your choice
Diamond	KRW 15,000,000~	
Platinum	KRW 10,000,000~	
Gold	KRW 5,000,000~	
Silver	KRW 3,000,000~	
Bronze	KRW 2,000,000~	
Honor	KRW 1,000,000~	

Date

Name

(Signature)



CONFERENCE OVERVIEW

Title	21st International SoC Design Conference (ISOCC 2024)
Theme	AI Fusion: SoC Convergence for Intelligent Ecosystems
Dates	August 19 (Mon.) - 22 (Wed.), 2024
Venue	Premier Hotel Tsubaki Sapporo, Hokkaido, Japan
Hosted by	The Institute of Semiconductor Engineers
Financial Sponsor by	IEEE Circuits and Systems Society
Expected No. of Papers	Approx. 100 Oral Papers, 60 Poster Papers
Expected No. of Participants	Approx. 500 participants from 15 countries
Official Language	English
Official Website	www.isocc.org

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